**Att. No. 1**

**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

1. InP SI 2” SSP 100 pieces
2. InP SI 4” SSP 25 pieces
3. **Parameters**

|  |  |  |  |
| --- | --- | --- | --- |
| Product name | | Parametrer | Specification |
| **2” InP Semi Insulating**  **Doped with Fe** | Diameter 2”  Thickness: 350±25 µm  Diameter: 50.8±0.4 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±0.5o |
| Secondary Flat | EJ (0-11) ±0.5o |
| Resistivity: | >1E7 ohm cm |
| EPD (Average): | ≤4 000/cm2 max |
| Surface Finish: | SSP (single side polished)  Side 1: Polished  Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |
| Product name | | Parametrer | Specification |
| **4” InP Semi Insulating**  **Doped with Fe** | Diameter 4”  Thickness: 625±25 µm  Diameter: 100±0.4 mm | Grade: | Prime, Epi-ready |
| Orientation: | (100)±0.3o |
| Primary Flat: | EJ (0-1-1) ±0.5o |
| Secondary Flat | EJ (0-11) ±0.5o |
| Resistivity: | >1E7 ohm cm |
| EPD (Average): | ≤10 000/cm2 max |
| Surface Finish: | SSP (single side polished)  Side 1: Polished  Side 2: Etched |
| Packaging: | ePAK, individual box, sealed with N2 in a moisture-stopping metallic foil bag, done in class 100 clean room. |